

Electrostatic Discharge Packaging Market Opportunity, Growth Drivers, Industry Trend Analysis, and Forecast 2025 – 2034

https://marketpublishers.com/r/E6CC70A1DBFAEN.html

Date: January 2025 Pages: 230 Price: US\$ 4,850.00 (Single User License) ID: E6CC70A1DBFAEN

Abstracts

The Global Electrostatic Discharge Packaging Market was valued at USD 2.49 billion in 2024 and is projected to grow at a CAGR of 5.6% from 2025 to 2034. As industries focus more on sustainability, the shift toward eco-friendly materials is playing a crucial role in driving market growth. Companies are increasingly adopting recycled materials and resource-efficient solutions to comply with environmental regulations and corporate sustainability goals. This growing demand for greener ESD protection products is fostering innovation, encouraging new packaging solutions that are both environmentally responsible and highly effective. With the rapid advancements in technology and the rising need to protect sensitive electronic components from static damage, the ESD packaging market is set for significant expansion over the coming decade.

Market segments within ESD packaging include conductive plastics, metal, dissipative plastics, and other materials. The conductive plastics segment, in particular, is expected to reach USD 1.5 billion by 2034. These materials are made from polymer-based substances infused with conductive fillers, ensuring an optimal balance of electrostatic protection, durability, and cost efficiency. They are lightweight yet robust, offering an essential solution for protecting sensitive components in sectors such as semiconductors and electronics, where even a small electrostatic discharge can lead to costly failures. The growing demand for conductive plastics is a testament to their versatility and effectiveness in safeguarding valuable electronics.

The market is also divided into anti-static, conductive, and static dissipative categories. The anti-static segment is expected to grow at the fastest rate, with a projected CAGR of 6% from 2025 to 2034. Anti-static materials are favored for their affordability and



versatility, making them a popular choice across multiple industries. These materials prevent static buildup, which is essential for packaging a wide range of electronic components and consumer goods. As businesses continue to look for costeffective, reliable solutions to mitigate the risks of electrostatic discharge, the adoption of anti-static materials is expected to surge.

North America held a 25% share of the global electrostatic discharge packaging market in 2024. The United States, in particular, is experiencing significant growth in demand for ESD packaging solutions. The country's expanding electronics, semiconductor, and manufacturing industries are key drivers of this trend. As a global leader in technology and innovation, the U.S. has high production and distribution volumes of electronic components, necessitating robust ESD protection measures. Stringent industry regulations and an increasing focus on preventing static-related damage are further contributing to the rapid expansion of the ESD packaging market in North America.



Contents

CHAPTER 1 METHODOLOGY & SCOPE

- 1.1 Market scope & definitions
- 1.2 Base estimates & calculations
- 1.3 Forecast calculations
- 1.4 Data sources
- 1.4.1 Primary
- 1.4.2 Secondary
- 1.4.2.1 Paid sources
- 1.4.2.2 Public sources

CHAPTER 2 EXECUTIVE SUMMARY

2.1 Industry synopsis, 2022-2034

CHAPTER 3 INDUSTRY INSIGHTS

- 3.1 Industry ecosystem analysis
 - 3.1.1 Factor affecting the value chain
 - 3.1.2 Profit margin analysis
 - 3.1.3 Disruptions
 - 3.1.4 Future outlook
 - 3.1.5 Manufacturers
 - 3.1.6 Distributors
- 3.2 Key news & initiatives
- 3.3 Regulatory landscape
- 3.4 Impact forces
 - 3.4.1 Growth drivers
 - 3.4.1.1 Rising demand for electronics and components
 - 3.4.1.2 Advancements in ESD packaging materials
 - 3.4.1.3 Increased focus on product protection
 - 3.4.1.4 Increasing emphasis on sustainable and eco-friendly materials
 - 3.4.1.5 Expansion of e-commerce drives packaging needs
 - 3.4.2 Industry pitfalls & challenges
 - 3.4.2.1 High costs of advanced ESD materials
 - 3.4.2.2 Limited recycling infrastructure for ESD packaging
- 3.5 Growth potential analysis



3.6 Porter's analysis

3.7 PESTEL analysis

CHAPTER 4 COMPETITIVE LANDSCAPE, 2024

- 4.1 Introduction
- 4.2 Company market share analysis
- 4.3 Competitive positioning matrix
- 4.4 Strategic outlook matrix

CHAPTER 5 MARKET ESTIMATES & FORECAST, BY MATERIAL TYPE, 2021-2034 (USD MILLION & KILO TONS)

- 5.1 Key trends
- 5.2 Conductive plastics
- 5.3 Metal
- 5.4 Dissipative plastics
- 5.5 Others

CHAPTER 6 MARKET ESTIMATES & FORECAST, BY PRODUCT TYPE, 2021-2034 (USD MILLION & KILO TONS)

- 6.1 Key trends
- 6.2 Bags and pouches
- 6.3 Trays
- 6.4 Boxes and containers
- 6.5 Tapes and labels
- 6.6 Foams
- 6.7 Others

CHAPTER 7 MARKET ESTIMATES & FORECAST, BY ESD CLASSIFICATION, 2021-2034 (USD MILLION & KILO TONS)

- 7.1 Key trends
- 7.2 Anti-static
- 7.3 Static dissipative
- 7.4 Conductive

CHAPTER 8 MARKET ESTIMATES & FORECAST, BY APPLICATION, 2021-2034



(USD MILLION & KILO TONS)

- 8.1 Key trends
- 8.2 Integrated circuits
- 8.3 Printed circuit boards (PCBs)
- 8.4 Electric vehicle (EV) components
- 8.5 Medical devices
- 8.6 Aerospace components
- 8.7 Sensors and modules
- 8.8 Others

CHAPTER 9 MARKET ESTIMATES & FORECAST, BY END USE INDUSTRY, 2021-2034 (USD MILLION & KILO TONS)

- 9.1 Key trends
- 9.2 Aerospace and defense
- 9.3 Automotive
- 9.4 Consumer electronics
- 9.5 Healthcare
- 9.6 Industrial machinery
- 9.7 Semiconductors
- 9.8 Others

CHAPTER 10 MARKET ESTIMATES & FORECAST, BY REGION, 2021-2034 (USD MILLION & KILO TONS)

10.1 Key trends 10.2 North America 10.2.1 U.S. 10.2.2 Canada 10.3 Europe 10.3.1 UK 10.3.2 Germany 10.3.3 France 10.3.4 Italy 10.3.5 Spain 10.3.6 Russia 10.4 Asia Pacific 10.4.1 China



10.4.2 India 10.4.3 Japan 10.4.4 South Korea 10.4.5 Australia 10.5 Latin America 10.5.1 Brazil 10.5.2 Mexico 10.6 MEA 10.6.1 South Africa 10.6.2 Saudi Arabia 10.6.3 UAE

CHAPTER 11 COMPANY PROFILES

- 11.1 ACL
- 11.2 Botron Company
- **11.3 Conductive Containers**
- 11.4 Delphon
- 11.5 Desco Industries
- 11.6 Dou Yee Enterprises
- 11.7 DS Smith
- 11.8 Elcom
- 11.9 GWP Conductive
- 11.10 Indepak
- 11.11 Nefab Group
- 11.12 Novapor Hans Lau
- 11.13 PoliCell
- 11.14 Protective Packaging
- 11.15 RS Components and Controls
- 11.16 Smurfit Kappa
- 11.17 Statclean Technology
- 11.18 Swissplast
- 11.19 Tegatai
- 11.20 Teknis
- **11.21 TRICOR**
- 11.22 XpertPack



I would like to order

Product name: Electrostatic Discharge Packaging Market Opportunity, Growth Drivers, Industry Trend Analysis, and Forecast 2025 – 2034

Product link: https://marketpublishers.com/r/E6CC70A1DBFAEN.html

Price: US\$ 4,850.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <u>https://marketpublishers.com/r/E6CC70A1DBFAEN.html</u>